

Case No.: AMKOR-017A  
Patent Appln.

#813  
BCC  
2-4-03



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Jong Sik Paek ✓	)	
		)	Group No.: 2812
Serial No.:	10/043,946 ✓	)	
		)	Examiner: Simkovic, Viktor
Filed:	01/11/2002 ✓✓	)	
		)	
For:	SEMICONDUCTOR PACKAGE	)	
	WITH STACKED DIES	)	

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON D C 20231

Dear Sir/Madam:

In response to the Office Action mailed October 24, 2002, in relation to the above identified patent application, please amend the application as follows:

In the Claims:

Please amend the following claims:

3. (Amended) The semiconductor package of Claim 1 wherein:

the conductive connectors comprise first and second conductive wires;

the bond pads of the first semiconductor die are electrically connected to respective ones of the first surfaces of the leads by the first conductive wires; and

the bond pads of the second semiconductor die are electrically connected to respective ones of the second surfaces of the leads by the second conductive wires.

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